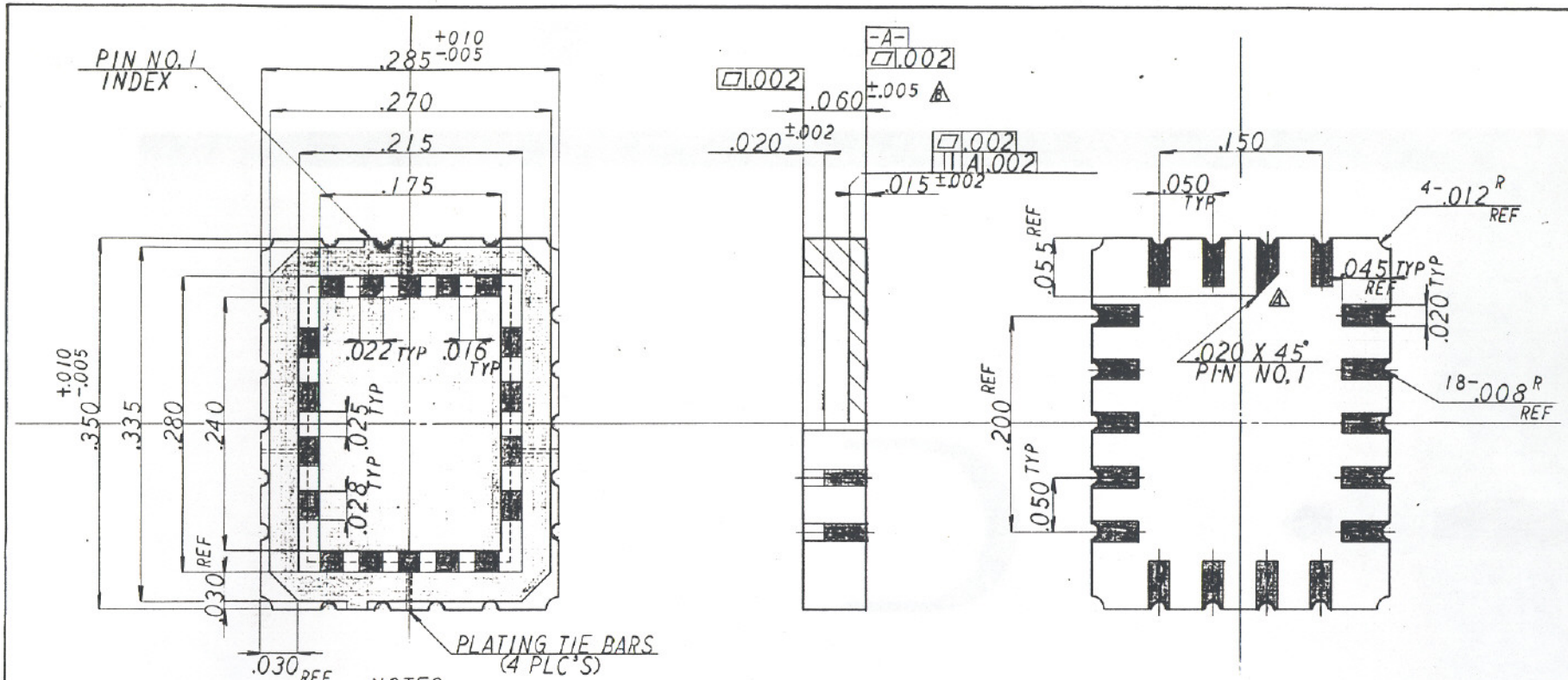

NOTES

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN THICKNESS OVER NICKEL PLATED
2. FLATNESS PERTAINS TO METALLIZED PADS ONLY
3. LEAD TO LEAD LEAKAGE MUST NOT EXCEED 5 NANO AMPS AT 100 V D.C
4. DIE ATTACH PAD SHALL BE ISOLATED FROM ANY LEADS (ZERO GROUND)

S=0
D=0

MTR-18CA

MODIFICATIONS				
⚠ CHANGED : .060 ±.007 → .060 ±.005	'82-4-8	O.M	N.U	
⚠ CHANGED INDEX MARK	'81-6-30	O.M	O.M	
CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME 18 LEAD CHIP CARRIER		TOLERANCES: UNLESS OTHERWISE SPECIFIED ±1 % N.L.T ±.005	DRAWN A. Komoto / CHECKED O. Matsuda
P/N			APPROVED / DATE
SCALE 10/1	MATERIAL CERAMIC KYOCERA A-440		'81-4-8
KYOTO CERAMIC CO., LTD. KYOTO JAPAN			DWG. PB-12916-B

PB-60894 MOD